



# Material Composition Declaration

## EPC2023

Company Name	Efficient Power Conversion (EPC)	Issue Date:	10/21/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0283	Contact Email:	yanping.ma@epc-co.com
Part Weight:	25.0 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	21.8755	87.37	89.71	873703
	Silicon oxide	7631-86-9	0.0843	0.34		3368
	Silicon nitride	12033-89-5	0.0272	0.11		1087
	Gallium nitride	25617-97-4	0.1032	0.41		4123
	Aluminum	7429-90-5	0.1697	0.68		6778
	Aluminum nitride	24304-00-5	0.0248	0.10		992
	Titanium	7440-32-6	0.0049	0.02		197
	Titanium nitride	25583-20-4	0.0163	0.07		653
	Copper	7440-50-8	0.0056	0.02		225
	Tungsten	7440-33-7	0.0085	0.03		341
	Polyimide		0.1407	0.56		5622
Under Bump Metal	Titanium	7440-32-6	0.0037	0.01	1.23	146
	Nickel	7440-02-0	0.1086	0.43		4336
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.1966	0.79		7851
Solder Bump	Tin	7440-31-5	2.2112	8.83	9.06	88315
	Silver	7440-22-4	0.0567	0.23		2264
	Copper	7440-50-8	0.0000	0.00		0
Sum in total:			25.0	100.00	100	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.